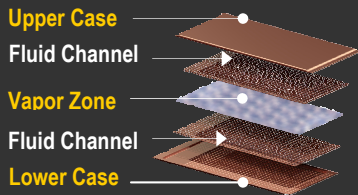


Celsia NanoSpreader¹ Vapor Coolers

NanoSpreader General Information



ENHANCED PERFORMANCE

Up to 30% better thermal performance than heat pipe solutions, with ten times the thermal conductivity and half the weight of solid copper

DESIGN VERSATILITY

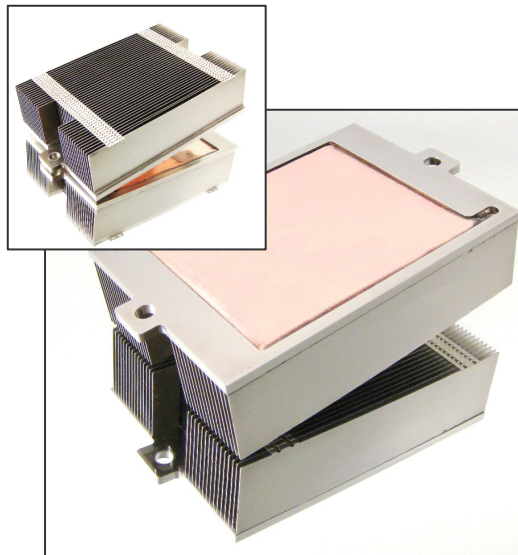
NanoSpreaders can be made as thin as 1.5mm with a very large surface area that is designed to come in direct contact with the heat source

IDEAL HEAT PIPE REPLACEMENT

Most heat pipe applications can be replaced with a NanoSpreader solution for less cost, better performance, and in some cases both

1U CPU Cooler for AMD Socket F

P/N: 401 AM 001



Better Performance: Designed in conjunction with AMD to provide 16% better thermal performance than solid copper / copper fin alternatives.

Lower Weight: Celsia AMD 1U socket F coolers weigh in at a mere 180 grams, as much as 62% less than copper solutions.

Improved Shock & Vibration: Stress analysis reveals that Celsia's lighter thermal solution results in a 300% reduction in motherboard strain over a solid copper base heat sink.

The Celsia CPU cooler for 1U servers using AMD socket F is designed to offer improved performance at an affordable price. Cooling enhancements are due to NanoSpreaders' large surface area and direct contact with the heat source.

This unique design allows for aluminum fins to be used in place of copper, lowering weight while reducing shock and vibration fatigue.

Contact Celsia to learn more about this solution along with other innovative VGA and memory cooling options.

Web: celsiatechnologies.com

US Contact: celsiasales@celsiatech.com

Asia Contact: elu@celsiatech.com

¹ NanoSpreader is a registered trademark of Celsia Technologies

Technical Data

- Materials: Copper, Aluminum and pure water
- Fin Attachment: Solder (lead free)
- Size: 116.5mm by 74.2mm x 28.1mm
- Recommended TIM: Shin-Etsu G-751
- Weight: 180 grams
- Maximum Clamping Force: 75 p.s.i.
- Operating Temperature: 20°C to 100 °C
- Thermal Shock Testing: 1000 Cycles at -35 °C to 80 °C
- High Temp. Testing: 200°C for 24 hours

celsia^o
TECHNOLOGIES™
Making Hot Technology Cooler®